



Material Content Data Sheet



Sales Product Name		IPD90N06S4-05		Issued		26. September 2017			
MA#		MA000484882							
Package		PG-TO252-3-11		Weight*		375.31 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.393	0.90	0.90	9041	9041	
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		574		
	inorganic material	phosphorus	7723-14-0	0.065	0.02		172		
	non noble metal	copper	7440-50-8	215.017	57.28	57.36	572908	573654	
wire	non noble metal	aluminium	7429-90-5	38.240	10.19	10.19	101891	101891	
encapsulation	organic material	carbon black	1333-86-4	0.923	0.25		2460		
	plastics	epoxy resin	-	16.160	4.31		43058		
	inorganic material	silicondioxide	60676-86-0	75.259	20.05	24.61	200525	246043	
leadfinish	non noble metal	tin	7440-31-5	3.787	1.01	1.01	10090	10090	
plating	non noble metal	nickel	7440-02-0	0.091	0.02		242		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	243	
solder	noble metal	silver	7440-22-4	0.074	0.02		197		
	non noble metal	tin	7440-31-5	0.059	0.02		157		
	non noble metal	lead	7439-92-1	2.822	0.75	0.79	7520	7874	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		51		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		15		
	non noble metal	copper	7440-50-8	19.177	5.11	5.12	51098	51164	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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